

Molded Interconnect Device Market Growth Forecast Supported by Rising Demand and Innovation

Molded Interconnect Device Market Size, Share and Research Report By Product Type (Antennae and Connectivity Modules, Sensors, Connectors and Switches

NEW YORK,, NY, UNITED STATES, July 30, 2026 /EINPresswire.com/ -- The Global [molded interconnect device market](#) reached an estimated USD 2.32 billion in 2025 and is projected to grow from USD 2.61 billion in 2026 to USD 6.88 billion by 2035, registering a CAGR of 11.35% during the forecast period.

Two major catalysts are accelerating this trajectory: the explosive miniaturization demands of next-generation consumer electronics and automotive ADAS systems, and the widespread adoption of laser direct structuring (LDS) technology that enables three-dimensional circuit integration within molded plastic components. With global electronic component complexity

“

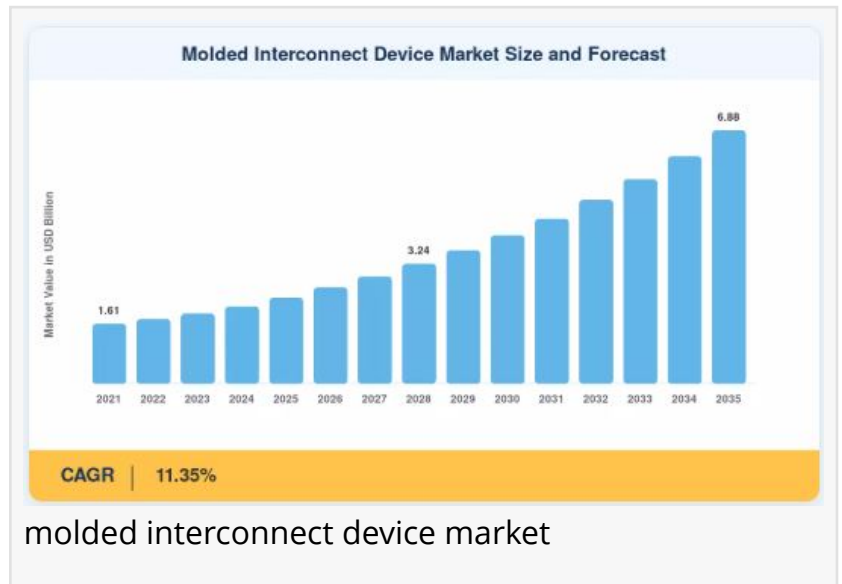
Molded Interconnect Device Market is expanding with the adoption of lightweight, compact, and high-performance electronic components in automotive, healthcare, and consumer electronics applications.”

*Market Research Future
(MRFR)*

escalating alongside the rise of IoT, 5G, and electrified transportation, manufacturers face mounting pressure to adopt MID solutions that consolidate mechanical and electrical functions or risk losing ground to faster, leaner competitors.

Legacy multi-component PCB-plus-housing assemblies many relying on labor-intensive manual wiring and discrete connector arrays are rapidly giving way to integrated MID platforms that embed antenna structures, sensor interfaces, and conductive traces directly within three-dimensional injection-molded substrates. A recent Fraunhofer Institute analysis estimated that top-quartile

[automotive OEMs](#) deploying LDS-based MID components achieved 31–36% part-count



reductions and 22% assembly cost savings compared to peers still relying on conventional PCB-and-housing architectures. This technology shift is not incremental it represents a fundamental reimagining of how electronic assemblies are designed, manufactured, and integrated across industries.

Get Full PDF Sample Copy of Report: (Including Full TOC, List of Tables & Figures, Chart) @ https://www.marketresearchfuture.com/sample_request/12327

□ How Significant Is the Molded Interconnect Device Market's Growth?

The molded interconnect device market has demonstrated consistent and robust expansion, rising from approximately USD 2.18 billion in 2021 to an estimated USD 2.32 billion in 2025, representing a healthy historical growth trajectory. The market is expected to more than double over the next decade, driven by accelerating adoption across automotive electronics, medical devices, consumer wearables, and telecommunications infrastructure all sectors where space efficiency and component integration are critical engineering priorities.

Surging demand for lightweight, compact electronic assemblies in electric vehicles, hearable devices, industrial automation controllers, and smart home products has created acute demand for MID platforms that replace multiple discrete components with single, multifunctional molded structures. Automotive OEMs, medical device manufacturers, consumer electronics brands, and industrial equipment producers are all investing heavily in MID design capabilities to reduce weight, shrink form factors, improve reliability, and accelerate time-to-market.

□ What Does the Future Hold for the Molded Interconnect Device Market?

Laser direct structuring and advanced in-mold electronics (IME) technologies stand at the forefront of the market's next growth phase. LDS-MID platforms are transforming electronic assembly from a planar, multi-part discipline into a fully three-dimensional design paradigm. Modern LDS processes activate thermoplastic substrates with laser precision, enabling fine-pitch antenna patterns, EMI shielding traces, and sensor contact pads to be plated directly onto complex 3D geometries eliminating separate PCBs, connectors, and housing brackets in a single manufacturing step.

The growing emphasis on in-mold electronics where functional inks, touch sensors, and even LED elements are embedded within injection-molded panels is another defining force shaping the market's future. Automotive interior designers, industrial HMI manufacturers, and consumer appliance brands are adopting IME to create seamless, backlit control surfaces that replace conventional button arrays and discrete display modules. The resulting assemblies offer superior aesthetic quality, improved environmental sealing, and significantly reduced component counts.

Additive manufacturing and hybrid [3D printing](#) of conductive traces on molded substrates is also

emerging as a complementary pathway, particularly for low-volume, high-complexity MID applications in aerospace, defense, and medical device prototyping. As materials science advances enable higher-conductivity inks and broader substrate compatibility, additive MID fabrication is expected to gain meaningful commercial traction through 2035.

Buy this Premium Research Report at:

https://www.marketresearchfuture.com/checkout?currency=one_user-USD&report_id=12327

□ Who Are the Key Players in the Molded Interconnect Device Market?

The molded interconnect device landscape is characterized by a mix of established electronic manufacturing specialists, materials science innovators, and vertically integrated component producers. Key participants shaping the competitive dynamics include:

- LPKF Laser & Electronics AG
- TE Connectivity
- Molex LLC
- Harting Technology Group
- Taoglas Group Holdings
- Jumatech GmbH
- MacDermid Alpha Electronics Solutions
- Solvay S.A.
- RTP Company
- Novatel Wireless (Inpixon)

Competition in the market is intensifying as vendors race to develop next-generation LDS additive materials capable of supporting higher-frequency 5G antenna designs, expand in-mold electronics process capabilities, and deepen partnerships with tier-1 automotive and medical device OEMs. Strategic acquisitions of specialty materials and precision laser processing companies are also reshaping the competitive landscape.

□ What Are the Emerging Trends in the Molded Interconnect Device Market?

Several transformational trends are redefining how the molded interconnect device market evolves through 2035:

5G Antenna Integration: LDS-MID platforms are becoming the preferred substrate for complex 5G mmWave and sub-6GHz antenna arrays in smartphones, automotive telematics units, and fixed wireless access equipment where spatial efficiency and antenna performance must be simultaneously optimized.

Automotive Electrification Demand: EV and ADAS system proliferation is driving unprecedented demand for MID-integrated radar sensor housings, LiDAR interface connectors, battery

management system components, and in-cabin lighting control modules across automotive production lines globally.

In-Mold Electronics (IME) Commercialization: The transition from prototyping to volume production of IME panels embedding capacitive touch, lighting, and heating elements directly within injection-molded surfaces is accelerating, particularly in automotive interior and industrial HMI applications.

Medical Device Miniaturization: Implantable device manufacturers and diagnostic equipment producers are adopting MID to consolidate electrode arrays, RF coils, sensor contacts, and housing structures within single biocompatible molded assemblies, driving both size reduction and reliability improvement.

Sustainability and Material Innovation: Bio-based and recyclable LDS-activatable thermoplastics are entering commercial qualification as OEMs respond to circular economy mandates and extended producer responsibility regulations across European and Asian markets.

Additive MID and Hybrid Manufacturing: Conductive inkjet printing, aerosol jet deposition, and laser-induced forward transfer (LIFT) techniques are enabling direct-write MID fabrication on non-planar substrates opening new design possibilities for low-volume and highly customized electronic assemblies.

Get access to the full description of the report @

<https://www.marketresearchfuture.com/reports/molded-interconnect-device-market-12327>

□ How Is the Molded Interconnect Device Market Segmented?

The molded interconnect device market report provides a comprehensive segmentation framework:

1 By Technology: Laser Direct Structuring (LDS), Two-Shot Molding (2K-MID), In-Mold Electronics (IME), Printing & Dispensing

2 By Material: LCP (Liquid Crystal Polymer), PA (Polyamide), ABS, PBT, Polycarbonate, Other Engineering Thermoplastics

3 By End-Use Industry: Automotive & Transportation, Consumer Electronics, Healthcare & Medical Devices, Telecommunications, Aerospace & Defense, Industrial Automation

4 By Application: Antennas & RF Components, Sensors & Actuators, Connectors & Contacts, Lighting Systems, Control Panels & HMI

5 By Geography: North America, Europe, Asia-Pacific, Middle East & Africa, South America

□ What Are the Regional Insights from the Molded Interconnect Device Market?

Europe commands approximately 38% of global molded interconnect device market share,

driven by Germany's dominant automotive and industrial electronics manufacturing base, the region's deep expertise in precision injection molding and laser processing, and the presence of key MID technology originators including LPKF Laser & Electronics. Stringent EU sustainability and miniaturization directives are further accelerating MID adoption across the region's automotive, medical, and industrial sectors.

Asia-Pacific holds the second-largest share at approximately 34%, with China, Japan, South Korea, and Taiwan representing the primary markets. The region's unparalleled consumer electronics manufacturing scale, rapidly expanding EV production base, and aggressive 5G infrastructure rollouts are creating massive structural demand for LDS-MID antenna components, automotive sensor housings, and IoT device interconnects.

North America represents a rapidly growing region, driven by automotive OEM electrification programs, expanding aerospace and defense MID adoption, and a thriving medical device manufacturing sector particularly in Minnesota, Massachusetts, and California. U.S. reshoring incentives under the CHIPS and Science Act are also stimulating domestic MID substrate and assembly capacity investments.

Middle East & Africa is projected to register the highest CAGR at approximately 9.6% through 2035, fueled by ambitious electronics manufacturing localization programs in Saudi Arabia and the UAE, growing defense electronics procurement, and investments in domestic telecommunications infrastructure incorporating MID-integrated antenna systems.

South America rounds out the global picture, with Brazil and Mexico representing the most active markets for MID technology adoption, primarily within automotive tier-1 supplier networks and consumer electronics assembly operations serving North American OEM customers.

□□□ Industry Analysis Reports by Market Research Future:

Community Banking Market-

<https://www.marketresearchfuture.com/reports/community-banking-market-23687>

Explosion Proof Equipment System Market-

<https://www.marketresearchfuture.com/reports/explosion-proof-equipment-system-market-23855>

Infrared Aerial Camera Market-

<https://www.marketresearchfuture.com/reports/infrared-aerial-camera-market-23858>

Balanced Funds Market-

<https://www.marketresearchfuture.com/reports/balanced-funds-market-23875>

Handheld Spectrum Analyzer Market-

<https://www.marketresearchfuture.com/reports/handheld-spectrum-analyzer-market-23894>

Integrated Microwave Assembly Market-

<https://www.marketresearchfuture.com/reports/integrated-microwave-assembly-market-23896>

Mpos Terminals Market-

<https://www.marketresearchfuture.com/reports/mpos-terminals-market-23919>

Pension Funds Market-

<https://www.marketresearchfuture.com/reports/pension-funds-market-23961>

Credit Agency Market-

<https://www.marketresearchfuture.com/reports/credit-agency-market-24072>

Engineering Insurance Market-

<https://www.marketresearchfuture.com/reports/engineering-insurance-market-24104>

Sagar Kadam

Market Research Future

+ + +1 628-258-0071

[email us here](#)

This press release can be viewed online at: <https://www.einpresswire.com/article/930180628>

EIN Presswire's priority is source transparency. We do not allow opaque clients, and our editors try to be careful about weeding out false and misleading content. As a user, if you see something we have missed, please do bring it to our attention. Your help is welcome. EIN Presswire, Everyone's Internet News Presswire™, tries to define some of the boundaries that are reasonable in today's world. Please see our Editorial Guidelines for more information.

© 1995-2026 Newsmatics Inc. All Right Reserved.